Quick start guide KIT_DRIVER_1EDN7550B

October 2018



Included in this kit

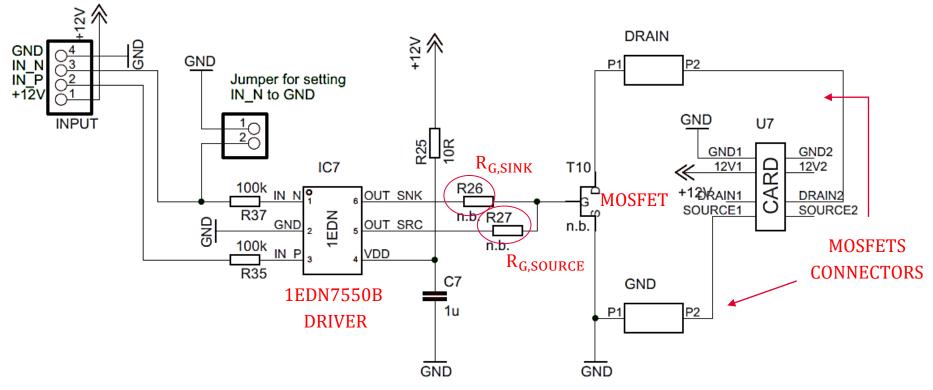




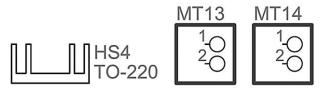


Board schematic

DRIVER INPUT CONNECTORS



HEATSINK



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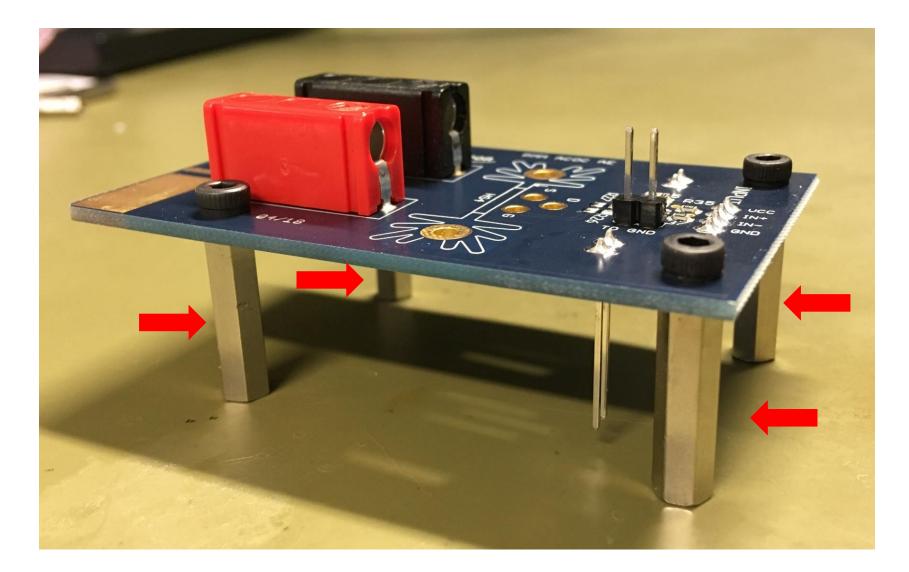
Components to add – BOM suggestion

Distance bolts	Screws for distance bolts	Screw and washer for MOSFET mounting to heatsink	TO-220 sockets
TO-220 MOSFET	Source resistor (R27)	Sink resistor (R26)	
	3980	33RC	

Component	Quantity	Designator	Comment	Voltage	Footprint	Туре	Part number/ supplies
Resistors	2	R26,R27			RES805R	SMD ceramic resistor	
TO-220 sockets	1	Т10	TO-220 socket		TO-220	Receptacle Connector 0.034" ~ 0.041" (0.86 mm ~ 1.04 mm)	5050865-5 Digi-key

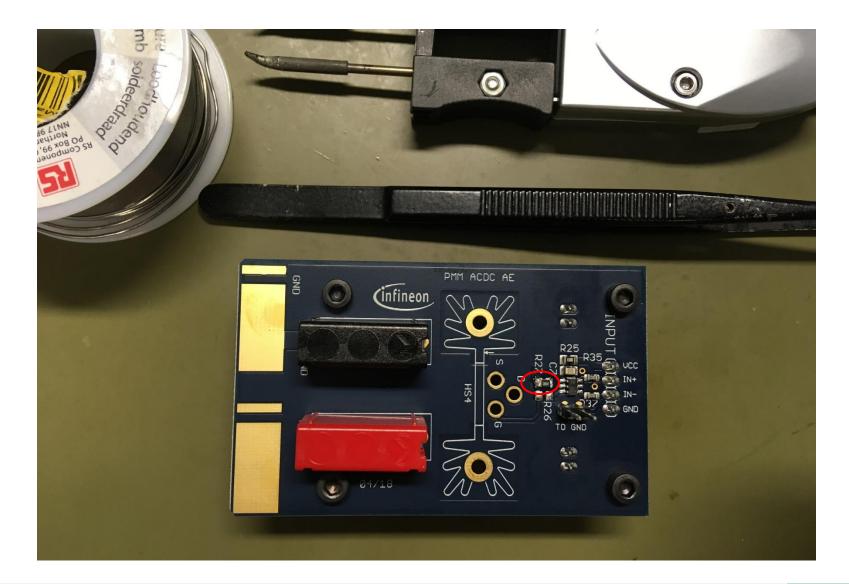


Step 1: Distance bolts mounting





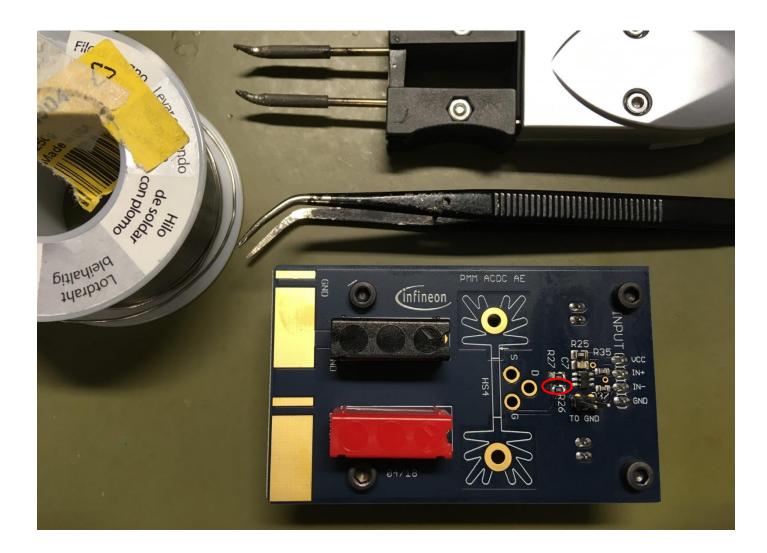
Step 2: Source resistor soldering



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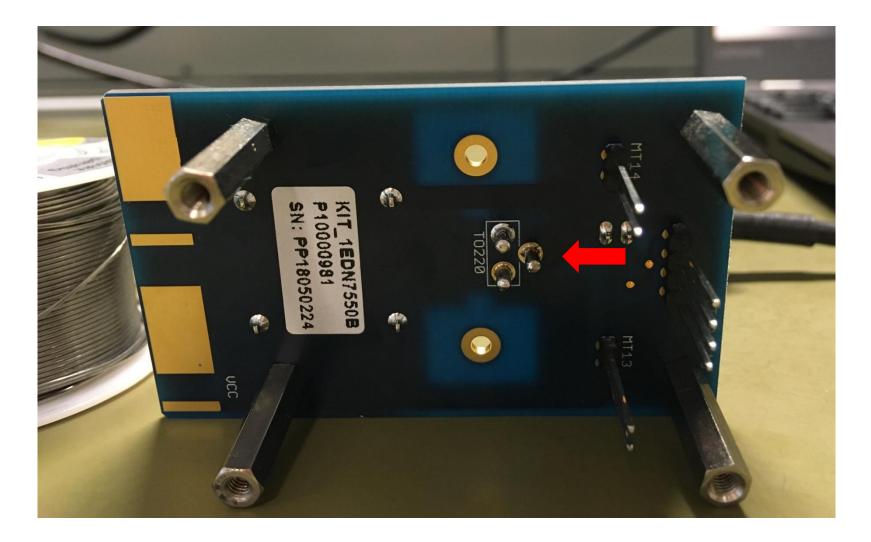
Step 3: Sink resistor soldering



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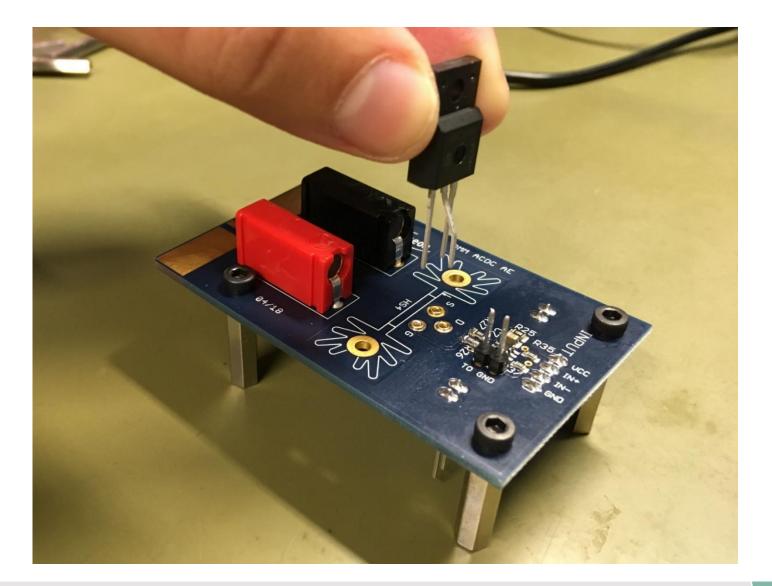


Step 4: TO-220 sockets soldering





Step 5: MOSFETs placement into the sockets



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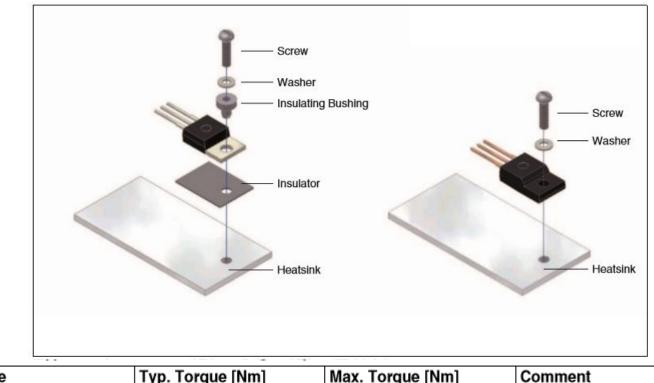
Step 6: Heatsink mounting (optional)

- > Solder the heatsink if the board is used in high voltage scenarios
- > In basic measurements it is not necessary
- See next slide for further information on how to properly mount the MOSFETs to the heatsink





TO-220 MOSFET mounting to the heatsink

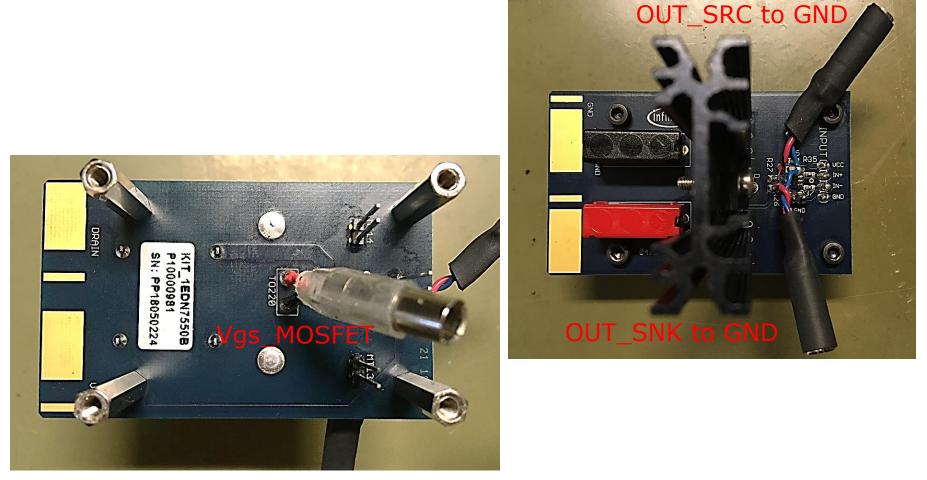


Package	Typ. Torque [Nm]	Max. Torque [Nm]	Comment
PG-TO220	0.6	0.7	Screw M3
PG-TO220 FullPAK	0.5	0.7	Screw M2.5

Recommendations for assembly of Infineon TO packages: <u>https://www.infineon.com/dgdl/Infineon-</u> <u>Package recommendations for assembly of Infineon TO packages-AN-v01 00-</u> <u>EN.pdf?fileId=db3a30431936bc4b011938532f885a38</u>



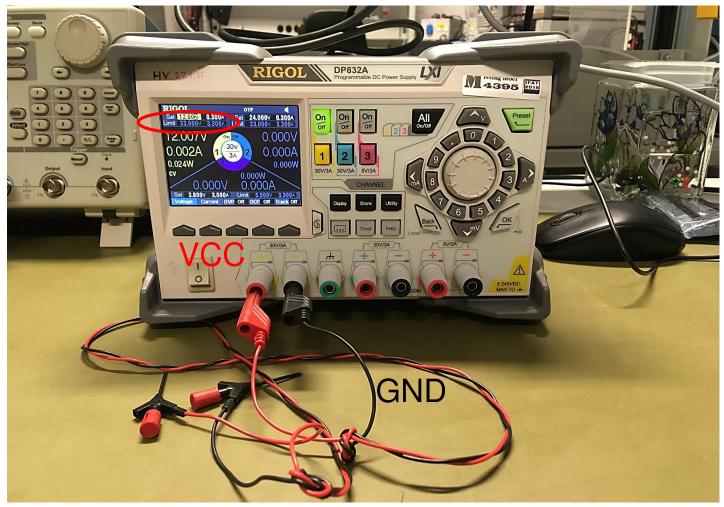
Step 7: BNC connectors soldering



 To measure the input PWM signal apply a differential voltage probe between the IN+ and IN- pins



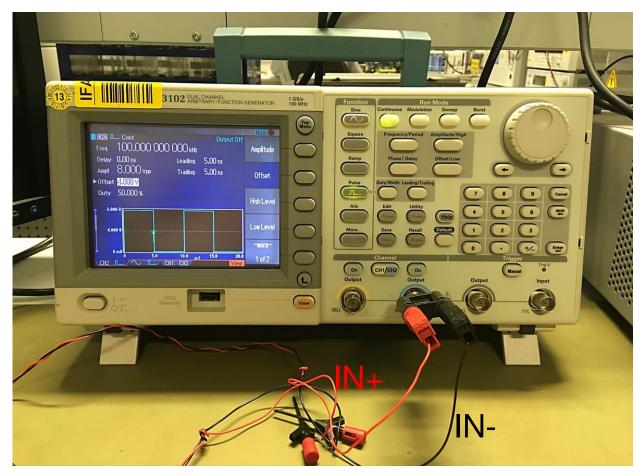
Instrumentation for driver supply generation



- V_{cc}=12 V for CoolMOS[™] and 8 V for OptiMOS[™]
- > Set the current limit below 1 A (0.3A e.g.)



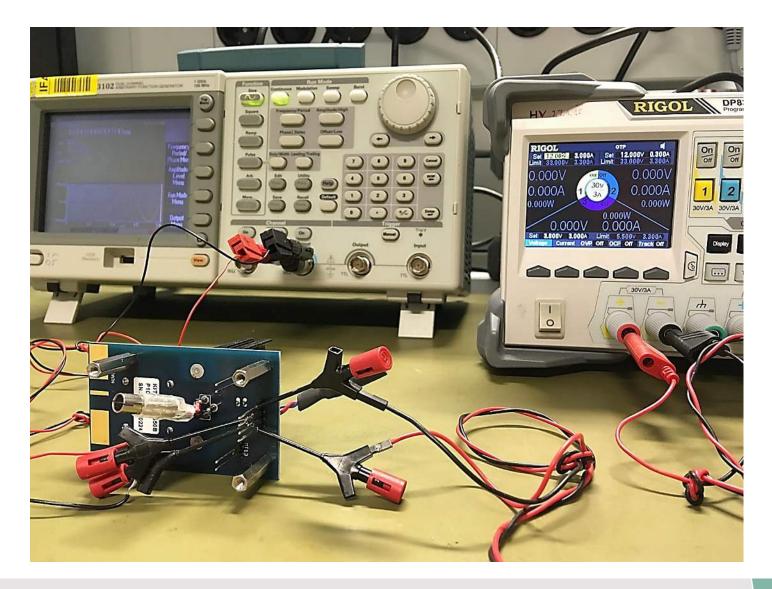
Instrumentation for PWM signals generation



- > Generate a PWM signal with at least 8 V amplitude
- > To generate a 3.3 V PWM signal change the input resistances R35,R37 to 33 k Ω
- > To generate a 5 V PWM signal change the input resistances R35,R37 to 52 k Ω



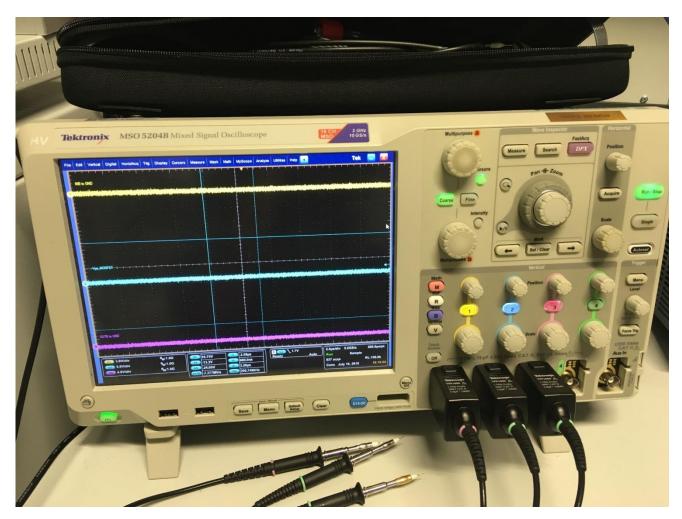
Connections



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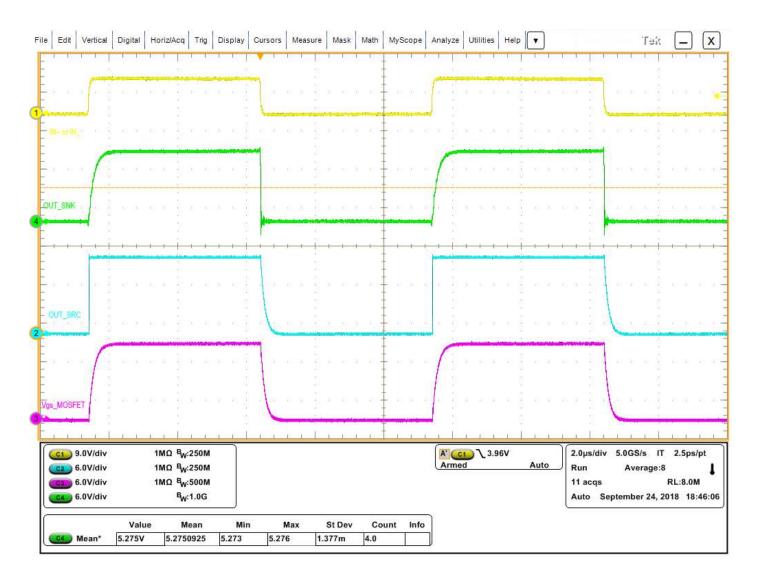
Instrumentation for signals evaluation



> Voltage probes used: Tetronix TPP1000 1 GHz, 3.9 pF



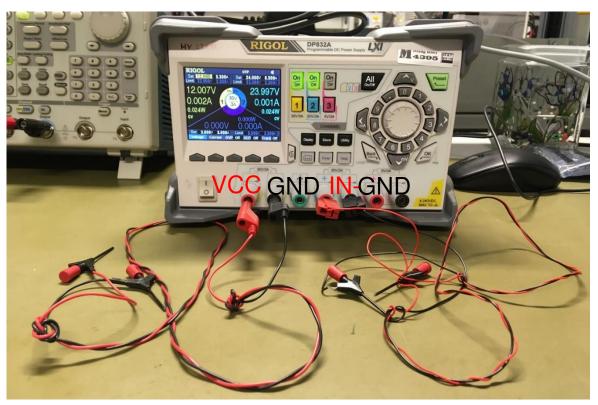
Oscilloscope waveforms



Evaluation of 1EDN7550B robustness to DC offsets: measurement setup



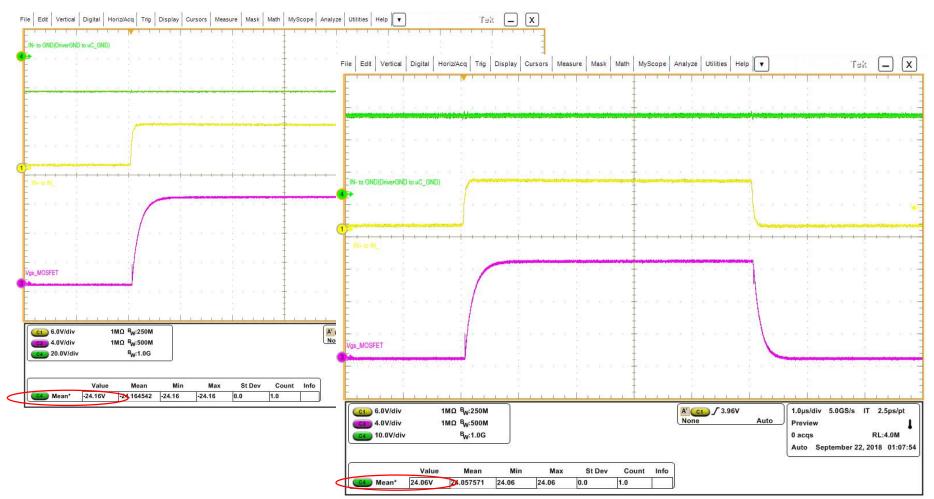
 The truly differential input 1EDN7550B gate driver is able to withstand DC offsets between the microcontroller ground (IN-) and the driver ground (GND)



- How to test: use the 2nd channel of the DC source generator to create an offset between INand GND
- How to measure: soldering a BNC connector between IN- and GND to measure the DC offset

Evaluation of 1EDN7550B robustness to DC offsets: measurement results





Conclusion: contrary to a standard 1-channel low-side driver, the 1EDN7550B properly turns ON and OFF with DC GND shifts between the microcontroller ground and the driver ground

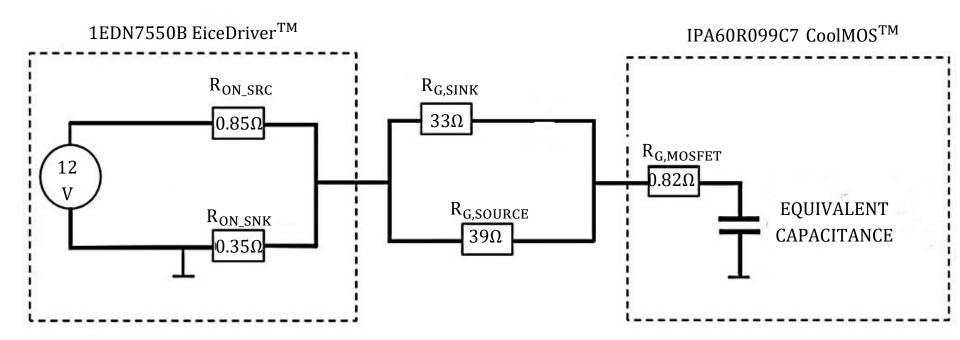


How – Changing the gate resistances and/or the gate MOSFET

What – Monitor the impact on the gate signal delivered to the MOSFET



Equivalent model of the driving circuit





C_{LOAD} calculation for IPA60R099C7



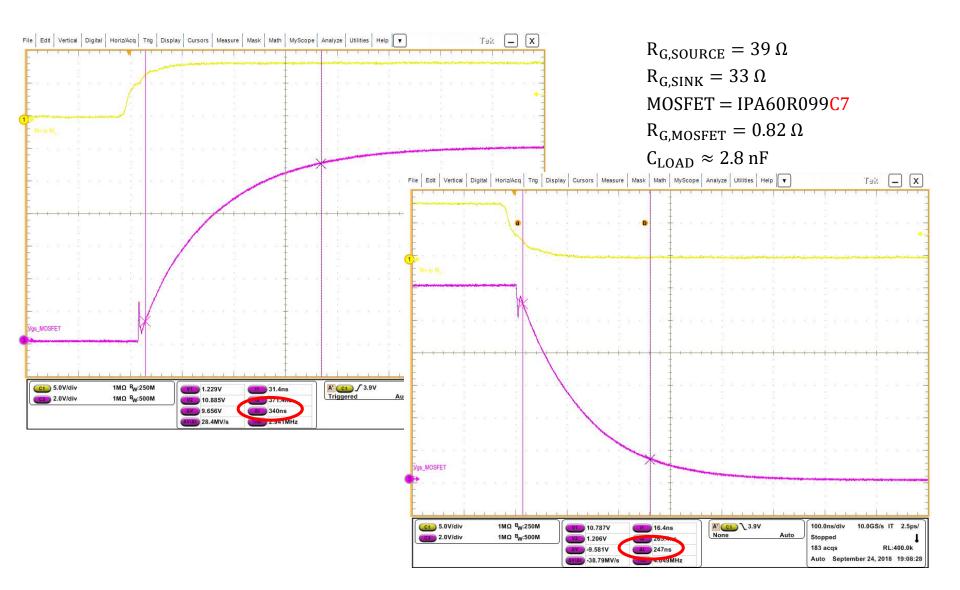
-		1	1	1	I	
Gate to drain charge	Q _{gd}	-	14	-	nC	V_{DD} =400V, I_{D} =9.7A, V_{GS} =0 to 10V
Gate charge total	Qg	-	42	-	nC	V_{DD} =400V, I_{D} =9.7A, V_{GS} =0 to 10V
	1	1	1	I	I	

$$Q_{LOAD} = Q_g - Q_{gd} = 28 nC \rightarrow C_{LOAD} = \frac{Q_{LOAD}}{V_{GS}} = 2.8 nF \text{ for } V_{GS} = 10 V \rightarrow C_{LOAD} = \frac{Q_{LOAD}}{V_{GS}} = 2.8 nF \text{ for } V_{GS} = 10 V \rightarrow C_{LOAD} = \frac{Q_{LOAD}}{V_{GS}} = 2.8 nF \text{ for } V_{GS} = 10 V \rightarrow C_{LOAD} = \frac{Q_{LOAD}}{V_{GS}} = 2.8 nF \text{ for } V_{GS} = 10 V \rightarrow C_{LOAD} = \frac{Q_{LOAD}}{V_{GS}} = 2.8 nF \text{ for } V_{GS} = 10 V \rightarrow C_{LOAD} = \frac{Q_{LOAD}}{V_{GS}} = 2.8 nF \text{ for } V_{GS} = 10 V \rightarrow C_{LOAD} = \frac{Q_{LOAD}}{V_{GS}} = 2.8 nF \text{ for } V_{GS} = 10 V \rightarrow C_{LOAD} = \frac{Q_{LOAD}}{V_{GS}} = 2.8 nF \text{ for } V_{GS} = 10 V \rightarrow C_{LOAD} = \frac{Q_{LOAD}}{V_{GS}} = 2.8 nF \text{ for } V_{GS} = 10 V \rightarrow C_{LOAD} = \frac{Q_{LOAD}}{V_{GS}} = 2.8 nF \text{ for } V_{GS} = 10 V \rightarrow C_{LOAD} = \frac{Q_{LOAD}}{V_{GS}} = 2.8 nF \text{ for } V_{GS} = 10 V \rightarrow C_{LOAD} = \frac{Q_{LOAD}}{V_{GS}} = 10 V \rightarrow C_{LOAD} = \frac{Q_{LOAD}}{V_{GS}} = 10 V + \frac{Q_{LOAD}}{V_{GS}} = 10 V$$

 $C_{LOAD} \approx 2.8 \, nF \, for \, V_{GS} = 12 \, V$

Rise/fall times





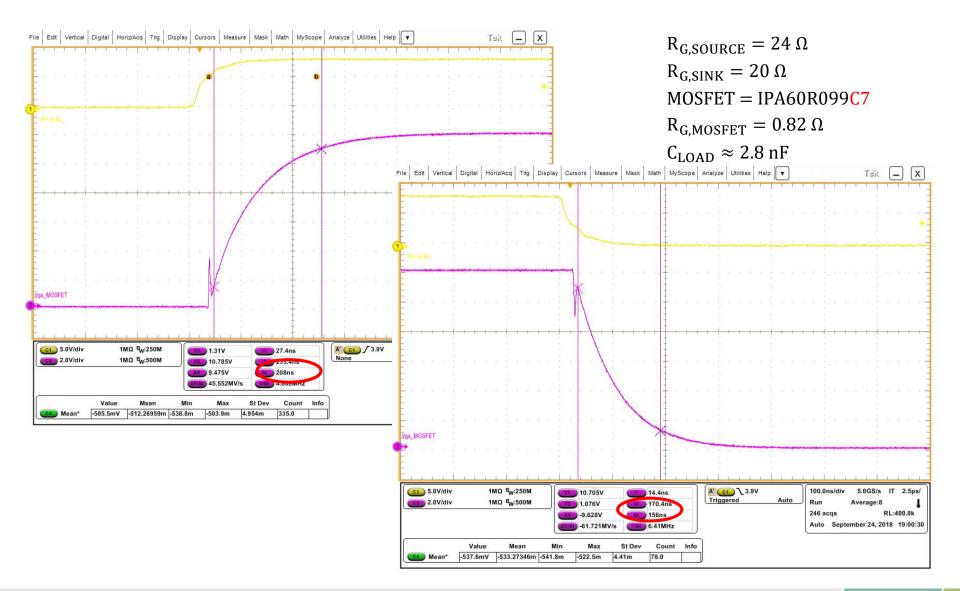


$R_{G,SOURCE} = 39 \Omega \rightarrow 24 \Omega$ $R_{G,SINK} = 33 \Omega \rightarrow 20 \Omega$

MOSFET = IPA60R099C7



Rise/fall times: New set of gate resistances



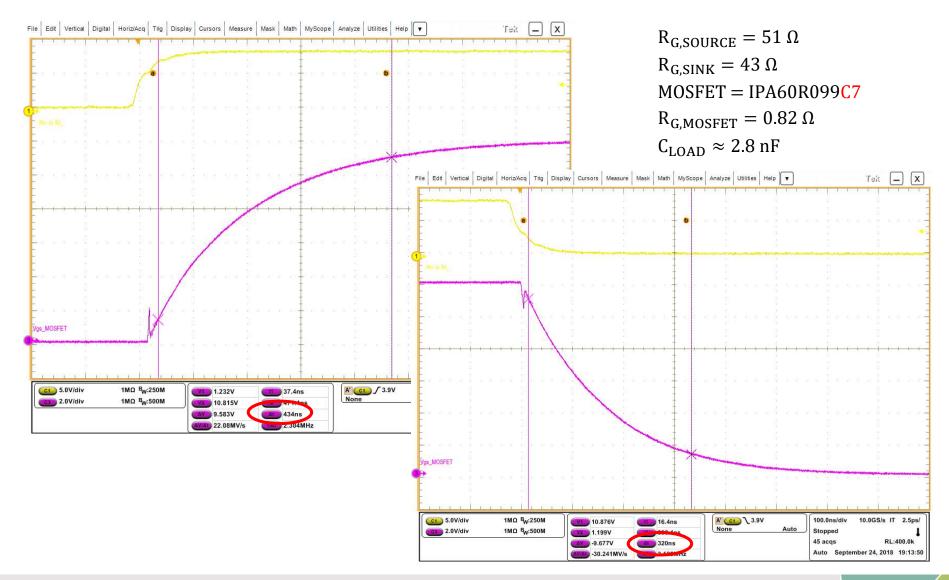


$R_{G,SOURCE} = 24 \Omega \rightarrow 51 \Omega$ $R_{G,SINK} = 20 \Omega \rightarrow 43 \Omega$

MOSFET = IPA60R099C7



Rise/fall times: New set of gate resistances





MOSFET replacement

P	T	
HACSA TONE	60R280F7	
		J. Maria

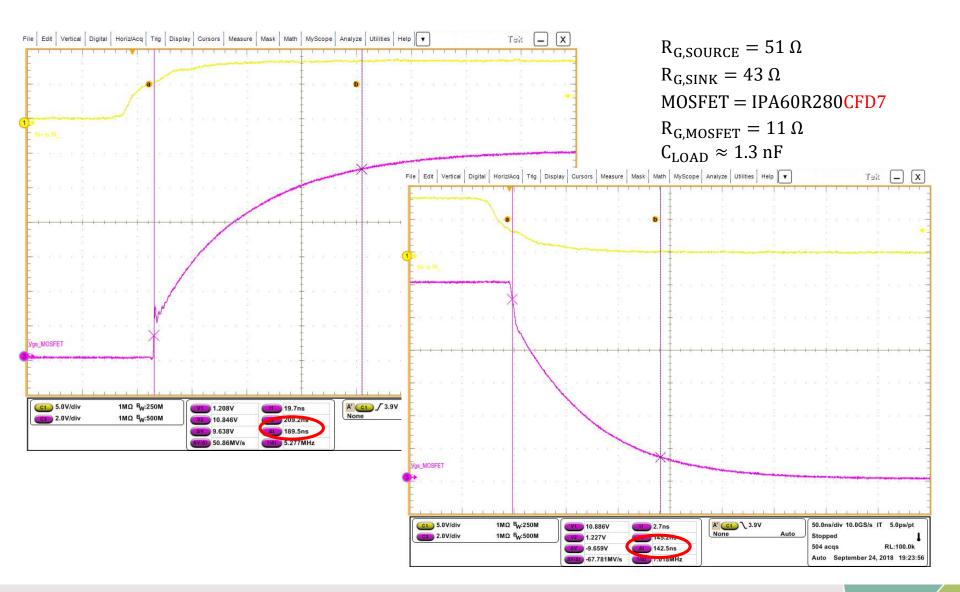
$IPA60R099C7 \rightarrow IPA60R280CFD7$

Gate to drain charge	Q _{gd}	-	5	-	nC	V_{DD} =400V, I_{D} =5.0A, V_{GS} =0 to 10V
Gate charge total	Qg	-	18	-	nC	V_{DD} =400V, I_{D} =5.0A, V_{GS} =0 to 10V

$$C_{LOAD} \approx \frac{13 \ nC}{10 \ V} = 1.3 \ nF \ for \ V_{GS} = 12 \ V$$



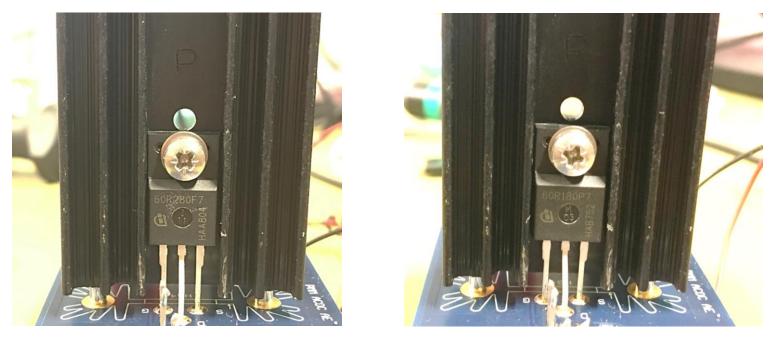
Rise/fall times: New MOSFET





MOSFET replacement

$IPA60R280CFD7 \rightarrow IPA60R180P7$

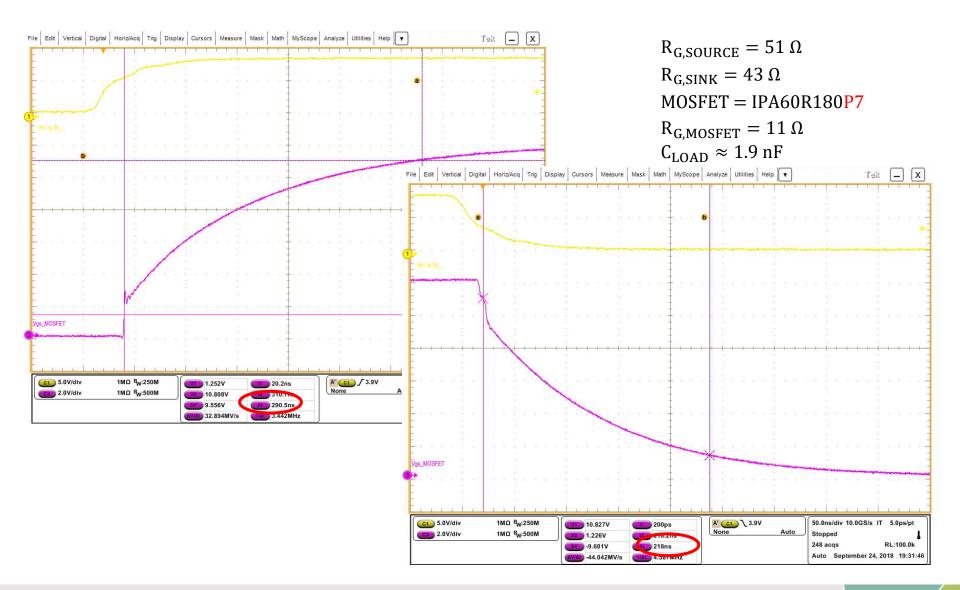


Gate to drain charge	Q _{gd}	-	8	-	nC	V _{DD} =400V, <i>I</i> _D =5.6A, <i>V</i> _{GS} =0 to 10V
Gate charge total	Qg	-	25	-	nC	V _{DD} =400V, <i>I</i> _D =5.6A, <i>V</i> _{GS} =0 to 10V

$$C_{LOAD} \approx \frac{19 \ nC}{10 \ V} = 1.9 \ nF \ for \ V_{GS} = 12 \ V$$



Rise/fall times: New MOSFET





Additional notes

- Note that the MOSFET is not turned-on or -off, you are only charging/discharging the gate-to-source capacitance
- Changing the gate resistors and the MOSFETs, you are changing the load for the driver
- If you want to turn-on or turn-off the MOSFET, you must integrate the board in a proper circuit
- You can not apply directly the voltage (e.g 400 V) across the MOSFET through the banana connectors on the board
- You must limit the input current from the DC source generator → add an inductance
- You must create a freewheeling path for the current when MOSFET is off

Example: boost converter, simple MOSFET in clamped inductive mode



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